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ABSTRACT

METHOD FOR SINGULATION OF SEMICONDUCTOR PACKAGE

Disclosed is a method for singulating a semiconductor package, which produces semiconductor devices of high quality without causing damage of semiconductor devices, thereby increasing the productivity, and can employ uniform vacuum stations irrespective of the sizes of the individual units produced, thereby lowering the production cost. The method comprises the steps of mounting the semiconductor package on a vacuum station; partially precutting the semiconductor package to a predetermined thickness by use of a dicing wheel; cleansing the semiconductor package to remove sludge therefrom, followed by drying the semiconductor package; and cutting the semiconductor package completely into individual units with the aid of a laser beam.

(Please note that Figure 6 is to accompany the abstract when published)

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